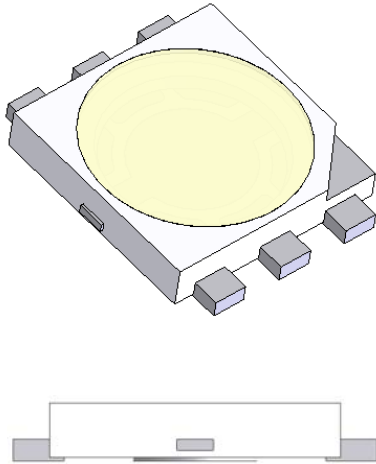




ProLight Opto
Technology Corporation



ProLight PP6N-TFFE
0.3W RGB LED
Technical Datasheet
Version: 2.6

Preliminary

Features

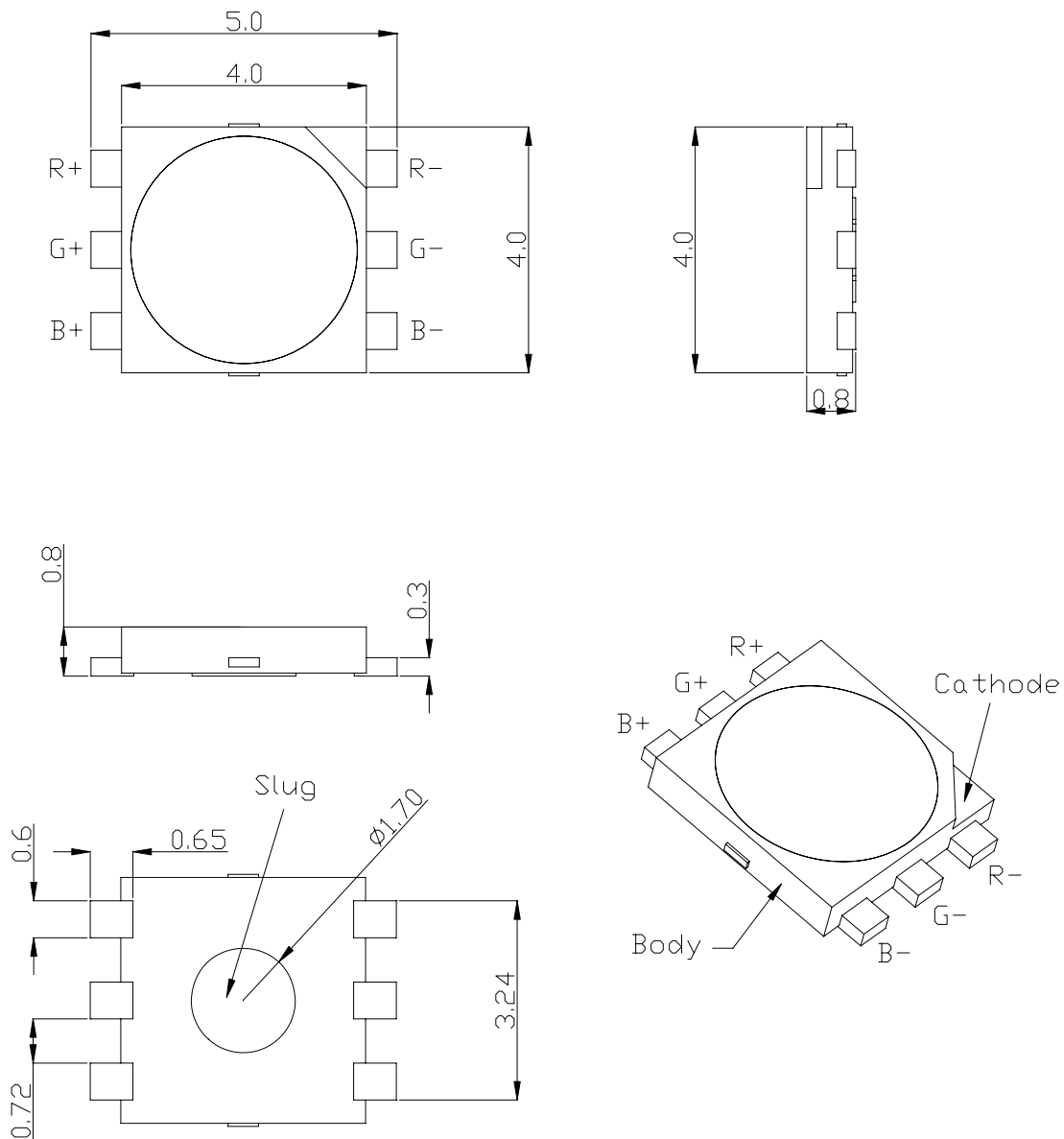
- R, G, B three color in one Package
- Very long operating life(up to 100k hours)
- Good color uniformity
- Industry best moisture sensitivity level - JEDEC 2a
4 week floor life without reconditioning
- Lead free reflow solder
JEDEC 020c compatible
- RoHS compliant
- More energy efficient than incandescent and
most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV

Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and
Residential Architectural
- Automotive Ext (Stop-Tail-Turn,
CHMSL, Mirror Side Repeat)
- LCD backlights

ProLight

Emitter Mechanical Dimensions



Notes:

1. The cathode side of the device is denoted by the chamfer on the part body.
2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
3. Drawing not to scale.
4. All dimensions are in millimeters.
5. All dimensions without tolerances are for reference only.
6. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

*The appearance and specifications of the product may be modified for improvement without notice.

Part Number

Color	Emitter	Beam Pattern
R/G/B	PP6N-TFFE	Lambertian

Flux Characteristics at 20mA, Junction Temperature T_j=25°C

Color	Minimum Luminous Flux (lm)	Typical Luminous Flux (lm)	Beam Pattern
Green	--	2.5	
Blue	--	0.5	Lambertian
Red	--	1.0	

Optical Characteristics at 20mA, Junction Temperature T_j=25°C

Color	Dominant Wavelength λ_D Color Temperature (CCT)			Spectral Half-width (nm) $\Delta\lambda_{1/2}$	Temperature Coefficient or Dominant Wavelength $\Delta\lambda_D/\Delta T_j$ (nm/°C)
	Min.	Typ.	Max.		
Green	520 nm	530 nm	540 nm	35	0.04
Blue	455 nm	465 nm	475 nm	25	0.04
Red	610 nm	620 nm	631 nm	20	0.05

Optical Characteristics at 20mA, Junction Temperature T_j=25°C (Continued)

Color	Beam Pattern	Total Included Angle $\theta_{0.9v}$ (degree)	Viewing Angle $2\theta_{1/2}$ (degree)	Typical Candela on Axis (cd)
Green		160	120	--
Blue	Lambertian	160	120	--
Red		160	120	--

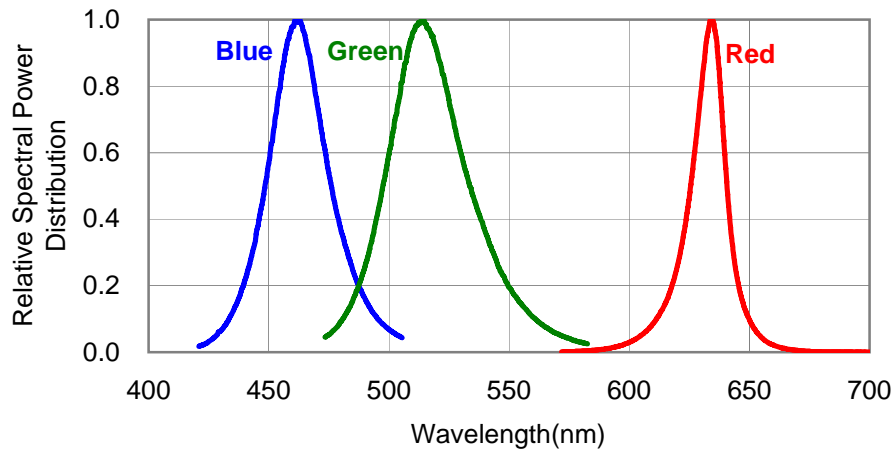
Electrical Characteristics at 20mA, Junction Temperature T_j=25°C

Color	Forward Voltage V _f (V)			Dynamic Resistance (Ω)	Temperature Coefficient of V _f (mV/°C) $\Delta V_f/\Delta T_j$	Thermal Resistance Junction to Slug (°C/W)
	Min.	Typ.	Max.			
Green	2.8	3.5	4.3	1.0	-2	10
Blue	2.8	3.5	4.3	1.0	-2	10
Red	1.9	2.2	3.1	2.4	-2	10

Absolute Maximum Ratings

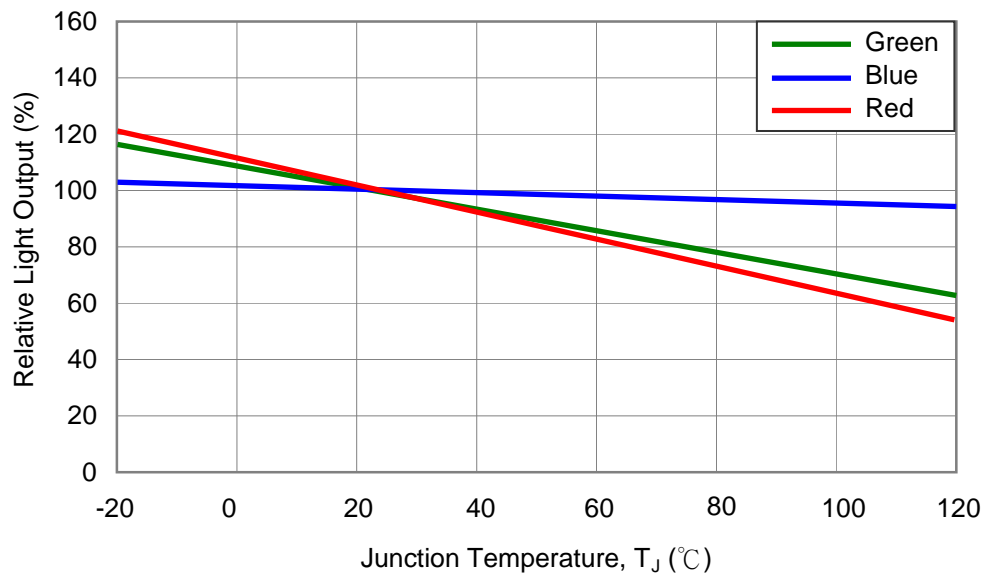
Parameter	Green/Blue	Red
DC Forward Current (mA)	20	20
Peak Pulsed Forward Current (mA)	100	100
Average Forward Current (mA)	20	20
LED Junction Temperature (°C)	135	120
Aluminum-core PCB Temperature (°C)	105	
Storage & Operating Temperature (°C)	-40 to +105	
Soldering Temperature (°C)	JEDEC 020c 260°C	

Color Spectrum, $T_J = 25^\circ\text{C}$



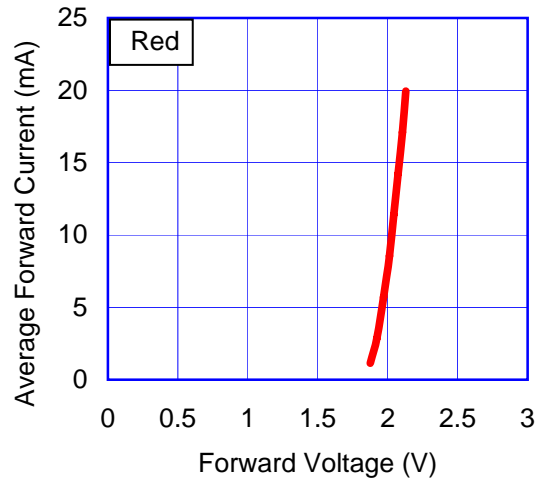
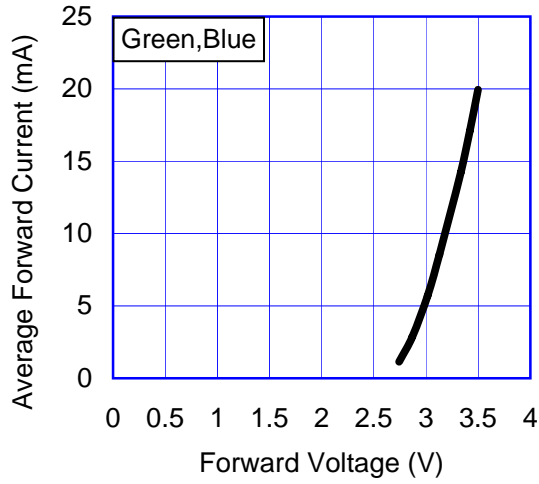
Light Output Characteristics

Relative Light Output vs. Junction Temperature

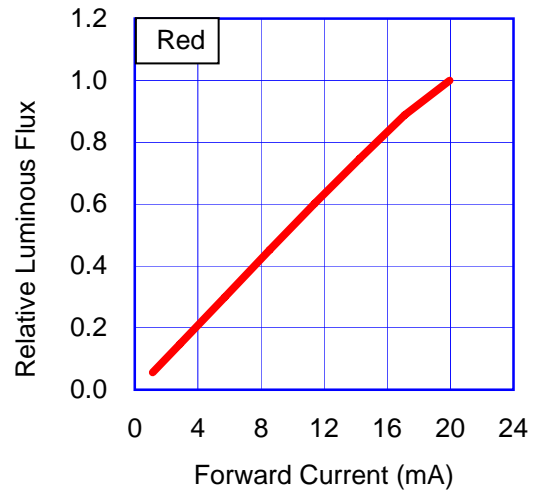
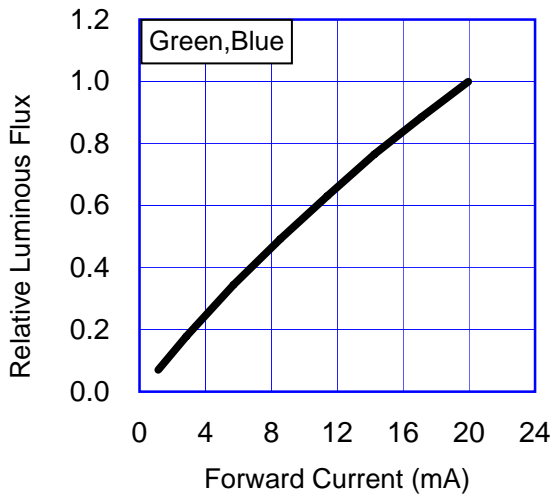


Forward Current Characteristics, $T_J = 25^\circ\text{C}$

1. Forward Voltage vs. Forward Current

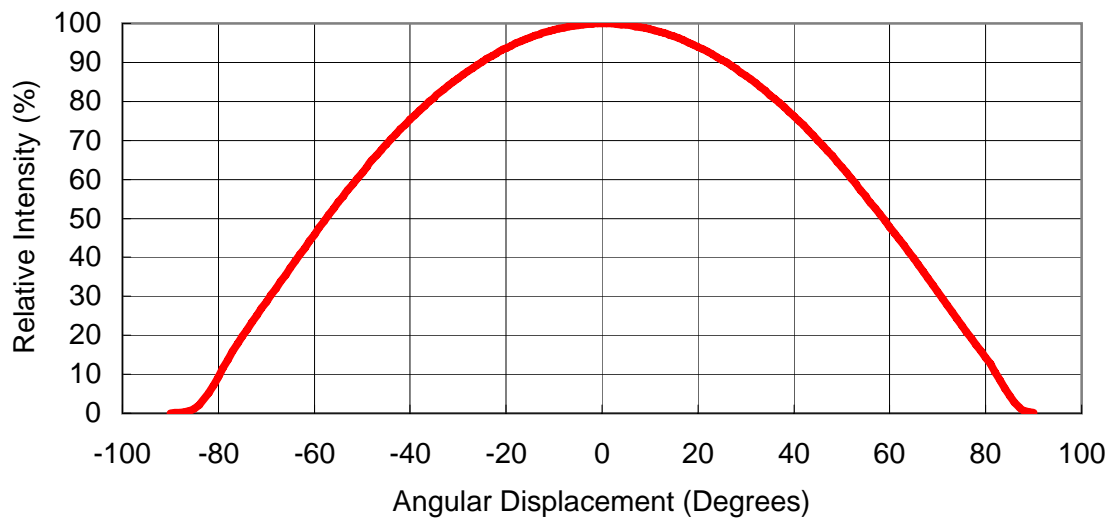


2. Forward Current vs. Normalized Relative Luminous Flux



Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Moisture Sensitivity Level - JEDEC 2a

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
2a	4 weeks	≤30°C / 60% RH	696 ² +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH

- The standard soak time includes a default value of 24 hours for semiconductor manufacture's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH		
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH		
2a	4 weeks	≤30°C / 60% RH	696 ² +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	≤30°C / 60% RH	192 ² +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	≤30°C / 60% RH	96 ² +5/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	≤30°C / 60% RH	72 ² +5/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	≤30°C / 60% RH	48 ² +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH		

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, $I_F = \text{max DC}$ (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, $I_F = \text{max DC}$ (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Non-operating Thermal Shock (TMSK)	-40°C to 120°C, 20 min. dwell, <20 sec. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

1. Depending on the maximum derating curve.
2. Criteria for judging failure

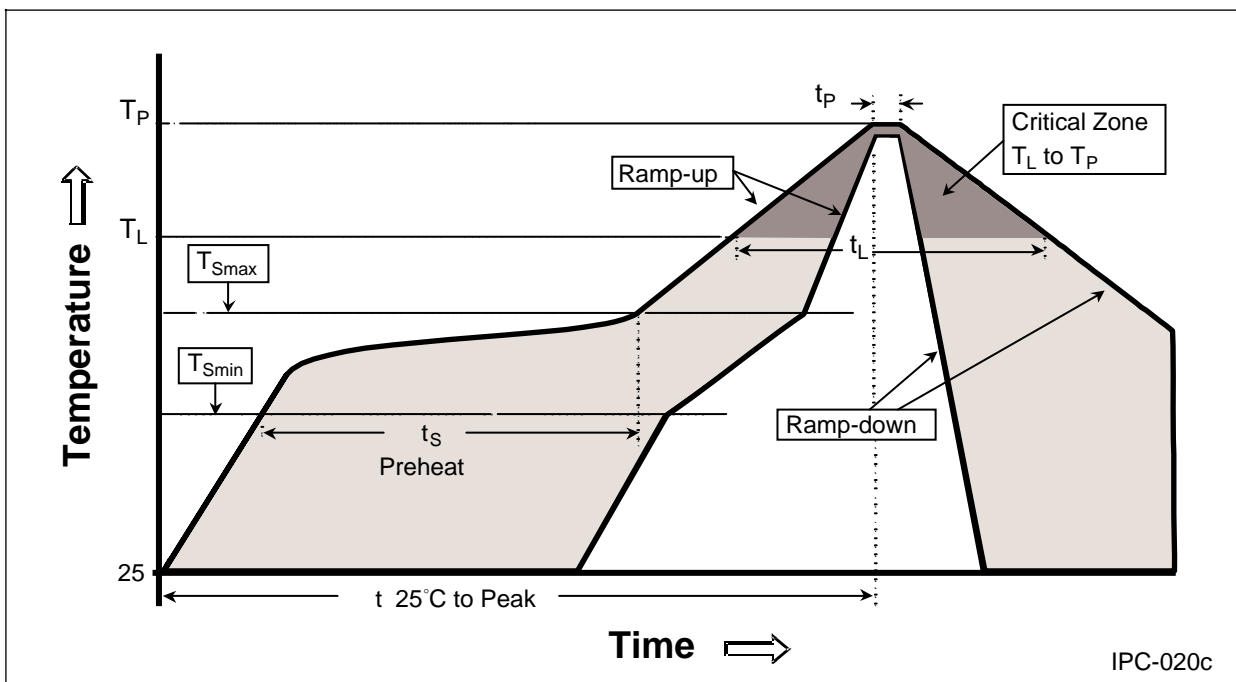
Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V_F)	$I_F = \text{max DC}$	-	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	$I_F = \text{max DC}$	Initial Level x 0.7	-
Reverse Current (I_R)	$V_R = 5V$	-	50 μA

* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

Reflow Soldering Condition - IPC/JEDEC J-STD-020C

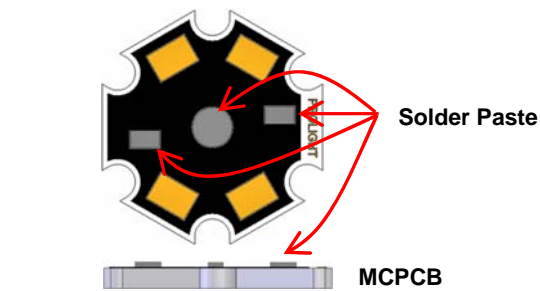
Profile Feature	Sn-Pb Eutectic Assembly	Lead(Pb)-Free Assembly
Average Ramp-Up Rate (T_{Smax} to T_P)	3°C / second max.	3°C / second max.
Preheat <ul style="list-style-type: none"> - Temperature Min (T_{Smin}) - Temperature Max (T_{Smax}) - Time (t_{Smin} to t_{Smax}) 	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: <ul style="list-style-type: none"> - Temperature (T_L) - Time (t_L) 	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classification Temperature (T_P)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



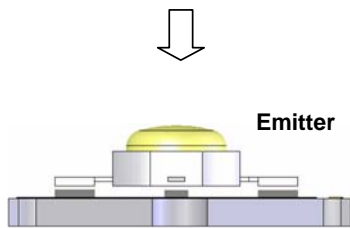
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Heat Plate Soldering Condition

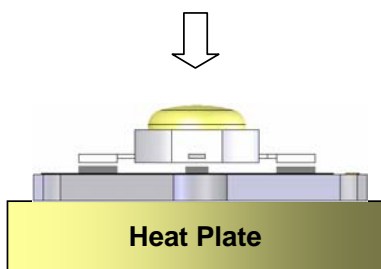
(1) Soldering Process for Solder Paste



Use Solder Mask to print Solder Paste on MCPCB.

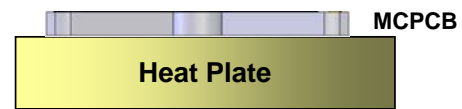


Place Emitter on MCPCB.

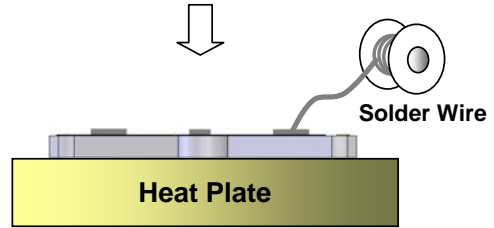


Put MCPCB on Heat Plate until Solder Paste melt.
The Solder Paste could be melted within 10 seconds.
Take out MCPCB out from Heat Plate within 15 seconds.

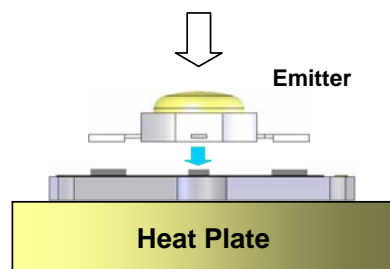
(2) Soldering Process for Solder Wire



Put MCPCB on Heat Plate.



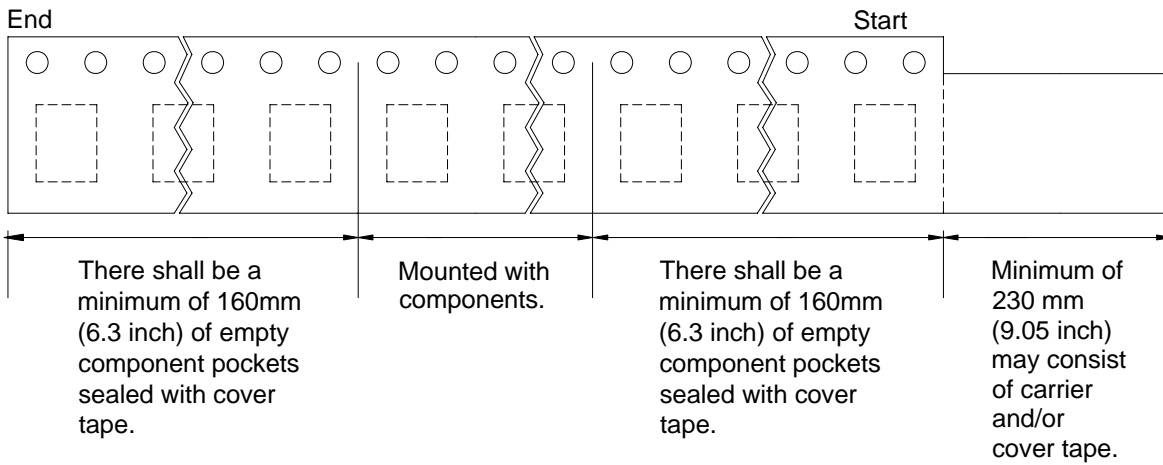
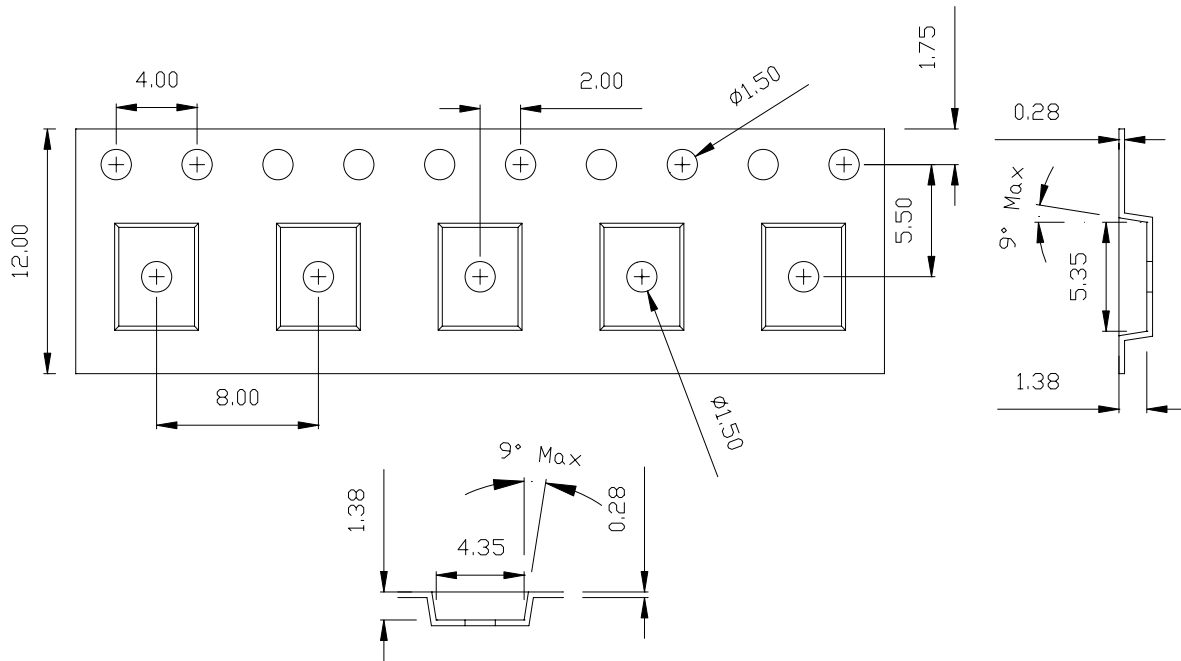
Place Solder Wire to the solder pad of MCPCB.



Put Emitter on MCPCB. Take the MCPCB out from Heat Plate within 10 seconds.

- Heat plate temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

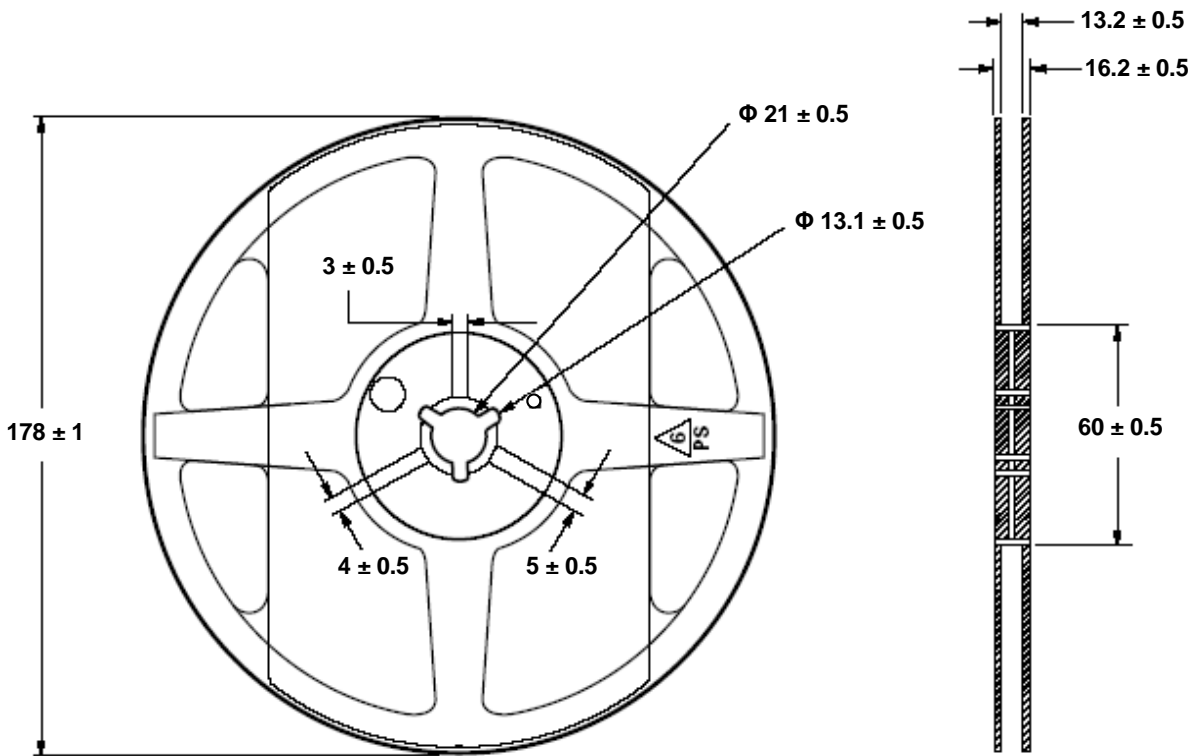
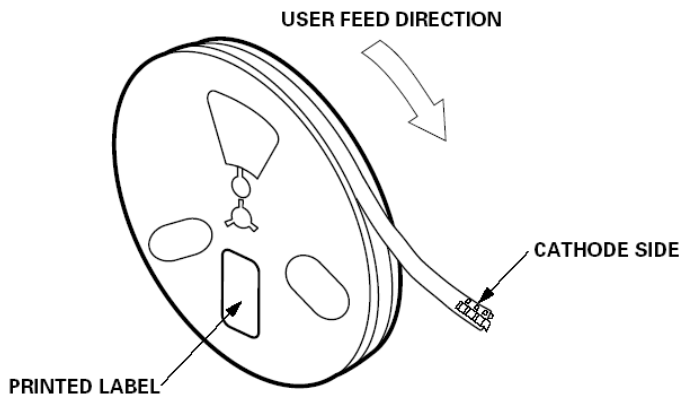
Emitter Reel Packaging



Notes:

1. Drawing not to scale.
2. All dimensions are in millimeters.
3. General tolerance is ± 0.10 mm.

Emitter Reel Packaging



Notes:

1. Empty component pockets sealed with top cover tape.
2. 250 or 500 pieces per reel.
3. Drawing not to scale.
4. All dimensions are in millimeters.

Precaution for Use

- Storage

Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

- The slug is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The slug is to be soldered. If not, please use the heat conductive adhesive.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decided after considering the package maximum temperature.
- The appearance and specifications of the product may be modified for improvement without notice.

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)